Application Data Sheet

Application Information

Application Type:: Regular

Subject Matter:: Utility

Suggested classification::

Suggested Group Art Unit::

CD-ROM or CD-R?:: None

Computer Readable Form (CRF)?:: No

Title:: WAFER HEAT-TREATMENT SYSTEM AND

WAFER HEAT-TREATMENT METHOD

Attorney Docket Number:: 025311-0115

Request for Early Publication?:: No

Request for Non-Publication?:: No

Suggested Drawing Figure:: 1

Total Drawing Sheets:: 3

Small Entity?:: No

Petition included?:: No

Secrecy Order in Parent Appl.?:: No

Applicant Information

Applicant Authority Type:: Inventor

Primary Citizenship Country:: Japanese

Status:: Full Capacity

Given Name:: Yoshimasa

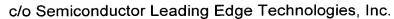
Family Name:: KAWASE

City of Residence:: Kanagawa

Country of Residence:: Japan

ļ, aļs
22
Ţħ.
[M
A 42
1
#
22
2
TU)

	· .	
Street of	mailing	address::



292 Yoshida-cho, Totsuka-ku, Yokohama

Kanagawa 244-0817, Japan

Country of mailing address::

Japan

Correspondence Information

Correspondence Customer Number:: 22428

E-Mail address::

wellis@foleylaw.com

Representative Information

Representative Customer	22428	
Number::		

Domestic Priority Information

Application::	Continuity Type::	Parent	Parent Filing
		Application::	Date::

Foreign Priority Information

Country::	Application number::	Filing Date::	Priority Claimed::
Japan	2001-036040	02/13/2001	Yes

Assignee Information

Assignee name::

SEMICONDUCTOR LEADING EDGE

TECHNOLOGIES, INC.